MECHANICAL CASE OUTLINE
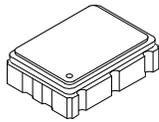## PACKAGE DIMENSIONS
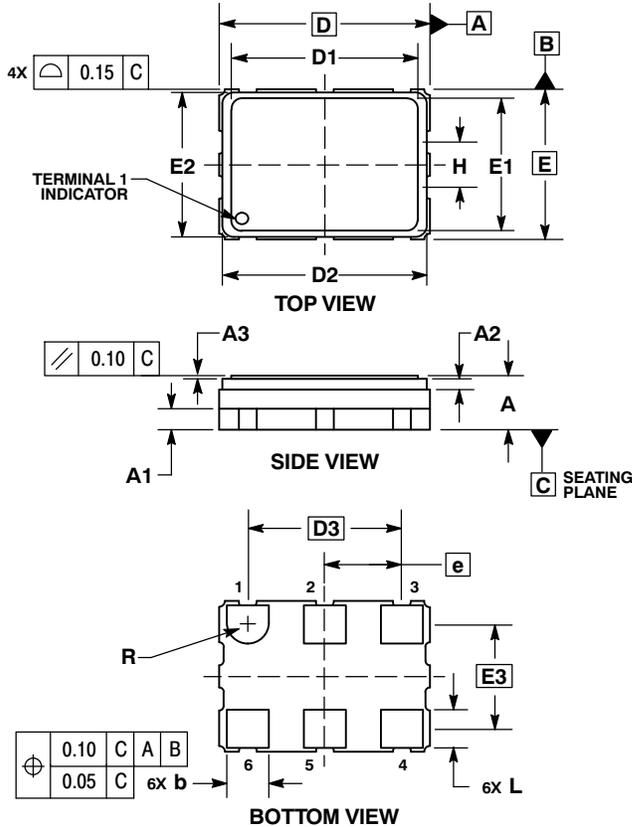
6 PIN CLCC, 7x5, 2.54P
CASE 848AB–01
ISSUE C

DATE 17 DEC 2007

SCALE 2:1

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

4X | 0.15 | C

TERMINAL 1 INDICATOR

TOP VIEW

0.10 | C

SEATING PLANE

SIDE VIEW

BOTTOM VIEW

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	1.70	1.80	1.90
A1		0.70 REF	
A2		0.36 REF	
A3	0.08	0.10	0.12
b	1.30	1.40	1.50
D		7.00 BSC	
D1	6.17	6.20	6.23
D2	6.66	6.81	6.96
D3		5.08 BSC	
E		5.00 BSC	
E1	4.37	4.40	4.43
E2	4.65	4.80	4.95
E3		3.49 BSC	
e		2.54 BSC	
H		1.80 REF	
L	1.17	1.27	1.37
R		0.70 REF	

GENERIC MARKING DIAGRAM*

XXXXXXXXX
XXXXXXXXXXXXX
AWLYYWWG
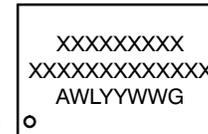
XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb–Free Package
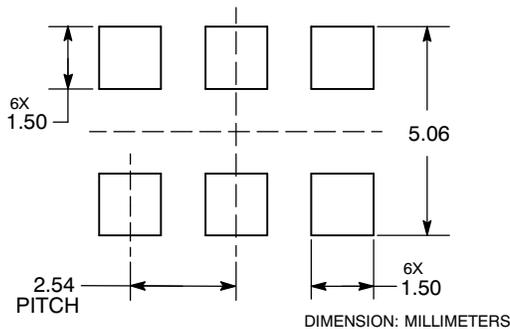
*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ▪ ", may or may not be present.

SOLDERING FOOTPRINT*

6X 1.50

5.06

2.54 PITCH

6X 1.50

DIMENSION: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON23467D	
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	6 PIN CLCC, 7X5, 2.54P	PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY C. REBELLO.	20 OCT 2006
A	CORRECTED DEVICE MARKING. REQ. BY C. REBELLO.	13 MAR 2007
B	REVISED DEVICE MARKING. REQ. BY C. REBELLO.	05 SEP 2007
C	ADDED BEVELS TO SIDES OF PACKAGE ON TOP AND BOTTOM VIEWS. ADDED H DIMENSION. REQ. BY P. CELAYA.	17 DEC 2007